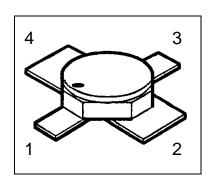


# **BFY182(ES)**

### **Features**

- For low noise, high-gain broadband amplifiers at collector currents from 1 mA to 20 mA
- Hermetically sealed microwave package
- f<sub>T</sub>= 8GHz
   F = 2.4 dB at 2 GHz



## **Product validation**

• **@esa** Space Qualified

ESCC Detail Spec. No.: 5611/006 Type Variant No. 04

# **Description**

**ESD**: Electrostatic discharge sensitive device, observe handling precautions!

**Table 1** Product information

Туре	Comment	Pin Config	Package			
		1	2	3	4	
BFY182(ES)	For flight use	_	_	Б	_	Miana V1
BFY182(P) <sup>1</sup>	Not for flight use <sup>1</sup>		E	В	E	Micro-X1

<sup>&</sup>lt;sup>1</sup> (P) parts have the same fit, form and function as (ES) parts, no screening acc. to Chart F3 in ESCC Generic Specification No. 5010

# **BFY182(ES)**

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# **Table of contents**

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# **BFY182(ES)**

**Maximum ratings** 



#### **Maximum ratings** 1

#### Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition	
		Min.	Тур.	Max.	1		
Collector-emitter voltage	$V_{\sf CEO}$	-	-	12	V		
Collector-emitter voltage	$V_{CES}$	-	-	20	V	V <sub>BE</sub> =0	
Collector-base voltage	$V_{CBO}$	-	-	20	V		
Emitter-base voltage	$V_{EBO}$	-	-	2	V		
Collector current	I <sub>C</sub>	-	-	35	mA		
Base current <sup>1</sup>	I <sub>B</sub>	-	-	4	mA		
Total power dissipation <sup>2</sup>	P <sub>tot</sub>	-	-	250	mW	<i>T</i> <sub>S</sub> ≤ 136 °C	
Junction temperature	T <sub>j</sub>	-	-	200	°C		
Operating temperature	Top	-65	-	200	°C		
Storage temperature	$\mathcal{T}_{stg}$	-65	-	200	°C		

 $<sup>^{1}</sup>$  The maximum permissible base current for  $V_{\text{FBE}}$  measurements is 20mA (spot-measurement duration < 1s)

 $<sup>^{2}</sup>$  For  $T_{S} > 136$  °C derating is required.  $T_{S}$  is measured on the collector lead at the soldering point to the PCB

**BFY182(ES)** 

Thermal characteristics



# 2 Thermal characteristics

## Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition	
		Min.	Тур.	Max.			
Thermal resistance, junction –soldering point	$R_{th,JS}$	-	-	255	K/W	T <sub>S</sub> is measured on the collector lead at the soldering point to the PCB	
Soldering Temperature	$T_{ m sol}$	-	-	250	°C	Duration 5 seconds maximum at a distance of not less than 0.5mm from the device body and the same lead shall not be resoldered until 3 minutes have elapsed.	

### **BFY182(ES)**

### **Electrical characteristics**



# 3 Electrical characteristics

at T<sub>A</sub>=25°C, unless otherwise specified

**Table 4** Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Collector-base cutoff current	I <sub>CBO</sub>	-	-	100	μΑ	$V_{\rm CB} = 20 \text{V}, I_{\rm E} = 0 \text{A}$
Collector-emitter cutoff current <sup>1</sup>	I <sub>CEX</sub>	-	-	200	μΑ	$V_{CE} = 12V, I_B = 0.2 \mu A$
Collector-base cutoff current	I <sub>CBO</sub>	-	-	50	nA	$V_{CB} = 10V, I_E = 0A$
Emitter base cuttoff current	I <sub>EBO</sub>	-	-	25	μΑ	$V_{\rm EB} = 2V, I_{\rm C} = 0A$
Emitter base cuttoff current	I <sub>EBO</sub>	-	-	0.5	μΑ	$V_{\rm EB} = 1 \text{V}, I_{\rm C} = 0 \text{A}$
Base-Emitter forward voltage	$V_{FBE}$	-	-	1	٧	$I_{\rm E}$ = 20mA, $I_{\rm C}$ = 0A
DC current gain	$h_{ extsf{FE}}$	55	100	170	-	$I_{\rm C} = 5  {\rm mA},  V_{\rm CE} = 6  {\rm V}$

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition	
		Min.	Тур.	Max.			
Transition frequency	$f_{T}$	6.5	7.5 8	-	GHz	$I_{C}$ = 15mA, $V_{CE}$ = 5V, $f$ = 500MHz $I_{C}$ = 15mA, $V_{CE}$ = 8V, $f$ = 500MHz	
Collector-base capacitance	ССВ	-	0.26	0.36	pF	V <sub>CB</sub> = 10V, V <sub>BE</sub> = vbe= 0, f= 1MHz	
Collector-emitter capacitance	C <sub>CE</sub>	-	0.34	-	pF	V <sub>CE</sub> = 10V, V <sub>BE</sub> = vbe= 0, f= 1MHz	
Emitter-base capacitance	C <sub>EB</sub>	-	0.8	1.1	pF	V <sub>EB</sub> =0.5V, V <sub>CB</sub> = vcb= 0, f= 1MHz	
Noise Figure	F	-	2.4	2.9	dB	$I_C$ = 5mA, $V_{CE}$ = 5V, $f$ = 2GHz, $Z_S$ = $Z_{Sopt}$	
Power Gain <sup>2</sup>	$G_{ma}$	13.5	14.5	-	dB	$I_C$ = 15mA, $V_{CE}$ = 5V, $f$ = 2GHz, $Z_S$ = $Z_{Sopt}$ , $Z_L$ = $Z_{Lopt}$	
Transducer gain	S <sub>21e</sub>   <sup>2</sup>	10	11	-	dB	$I_{C}$ = 15mA, $V_{CE}$ = 5V, $f$ = 2GHz, $Z_{S}$ = $Z_{L}$ = 50 $\Omega$	

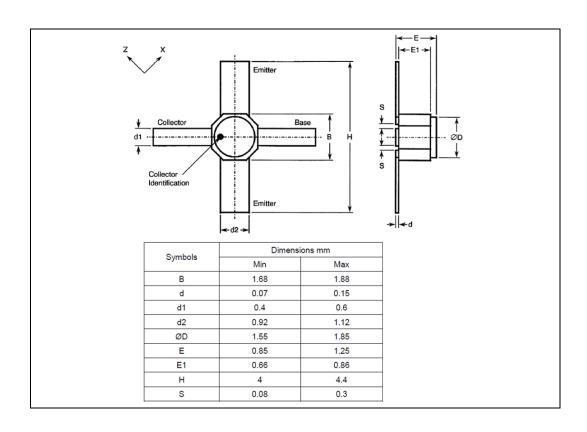
<sup>&</sup>lt;sup>1</sup> This test assures  $V_{(BR)CE0} > 12V$ 

 $<sup>^{2}</sup>G_{ma} = \left| \frac{S21}{S12} \right| (k - \sqrt{k^{2} - 1}), G_{ms} = \left| \frac{S21}{S12} \right|$ 

### **Package outlines**



# 4 Package outlines



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